



# APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
<p><b>TO:</b></p> <p><b>Part No.:</b></p> <p><b>Customer's Part No.:</b></p>	<p>Please return this copy as a certification of your approval</p> <p><b>Checked &amp; Approved by:</b></p> <p><b>Date:</b></p>

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Part No.	:	SF1165
Pages	:	6
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Revision	:	1.0

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**Application**

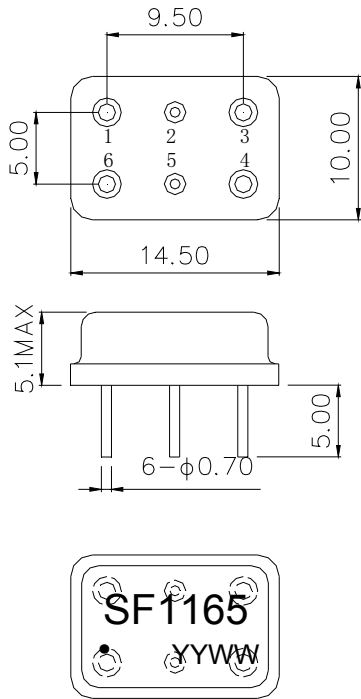
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 1 MHz

**Features**

- RoHS compatible
- Package size 14.5x10.0x5.10mm<sup>3</sup>
- Package Code DIP1510J
- Electrostatic Sensitive Device(ESD)



**Package Dimensions (Unit: mm)**



**Pin Configuration**

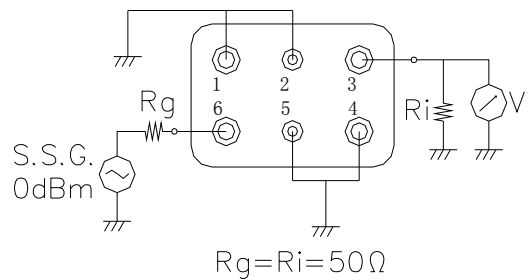
Pin No.	Description
6	Input
3	Output
1,2,4,5	Ground

**Marking Description**

<b>S</b>	Trademark
<b>F</b>	SAW Filter
<b>1165</b>	Part Number
●	Pin 1
<b>YYWW</b>	Year Code & Week Code

\*Fig: If the products produced in 06<sup>th</sup> week of 2012, The year code & week code is 1206.

**Test Circuit**



**Performance****Maximum Rating**

Item		Value	Unit
DC Voltage	$V_{DC}$	3	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	$T_{stg}$	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm

**Electronic Characteristics**

Test Temperature:  $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$

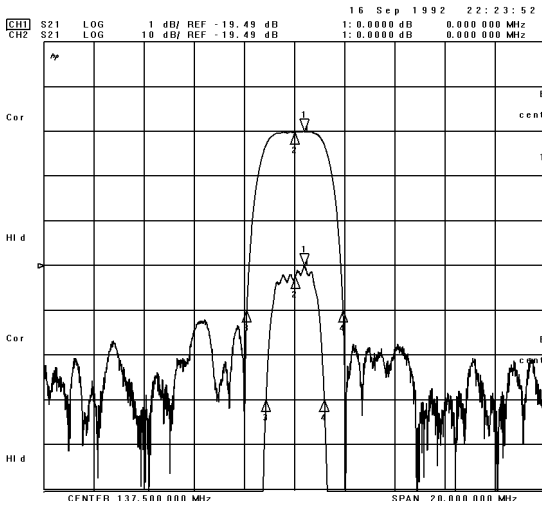
Terminating source impedance:  $50\Omega$

Terminating load impedance:  $50\Omega$

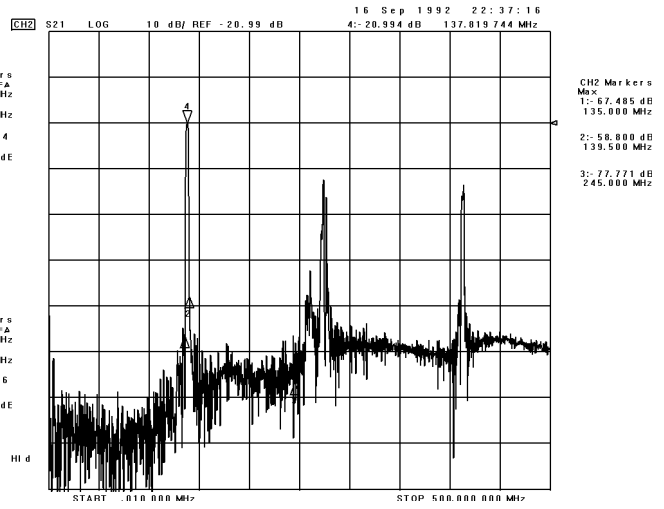
Item		Minimum	Typical	Maximum	Unit
Center Frequency	$f_c$	137.4	137.5	137.6	MHz
Insertion Loss(min)	IL		19.5	20.0	dB
Amplitude Ripple (p-p) 136.70-138.30MHz	$\Delta\alpha$		0.8	1.0	dB
1 dB Bandwidth	$BW_{1dB}$	1.80	1.85		MHz
Absolute Attenuation	$\alpha$				
	DC -135.50 MHz	40.0	45.0		dB
	139.50-240.00MHz	40.0	45.0		dB

Frequency Characteristics

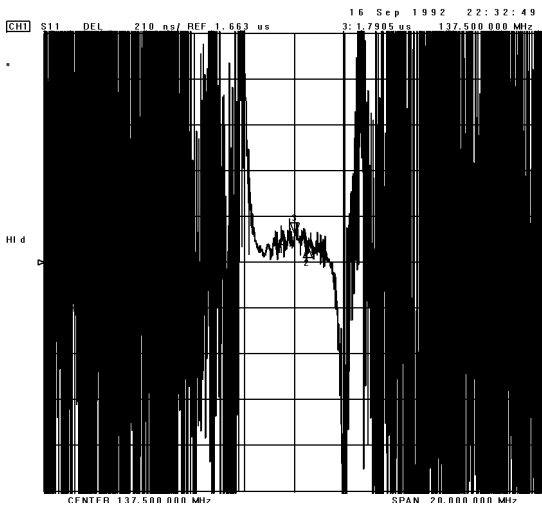
Frequency Response



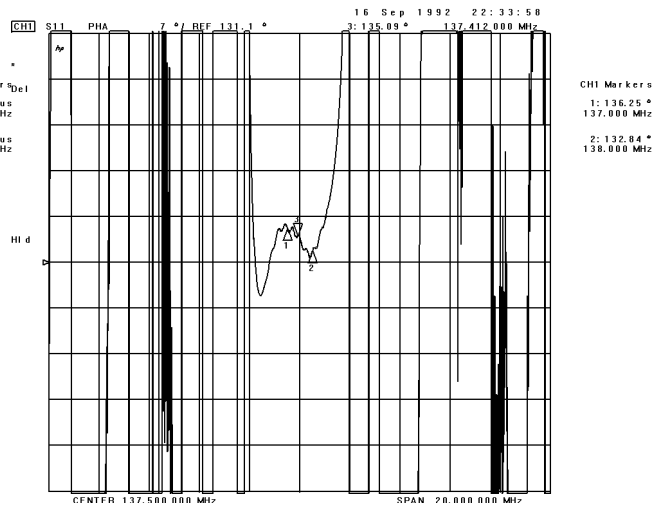
Frequency Response (wideband)



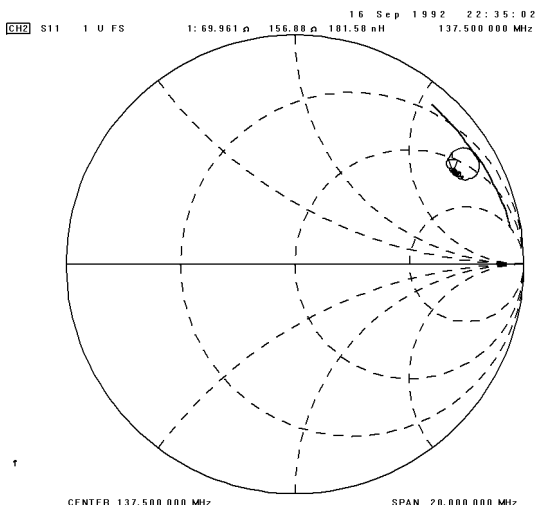
Delay Ripple



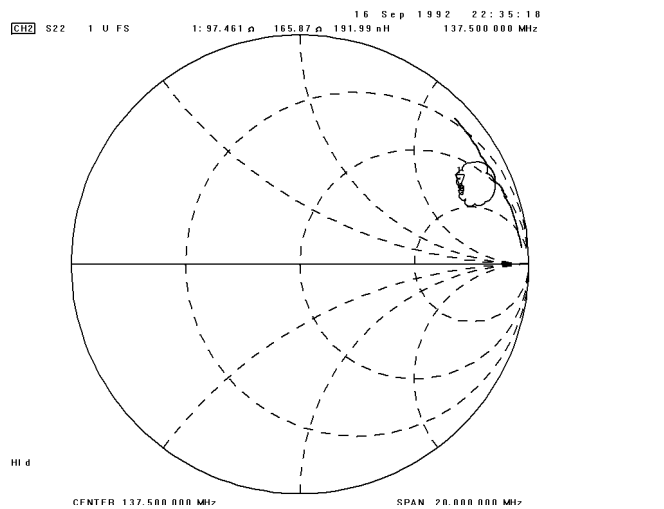
Phase Linearity



S11 Smith Chart



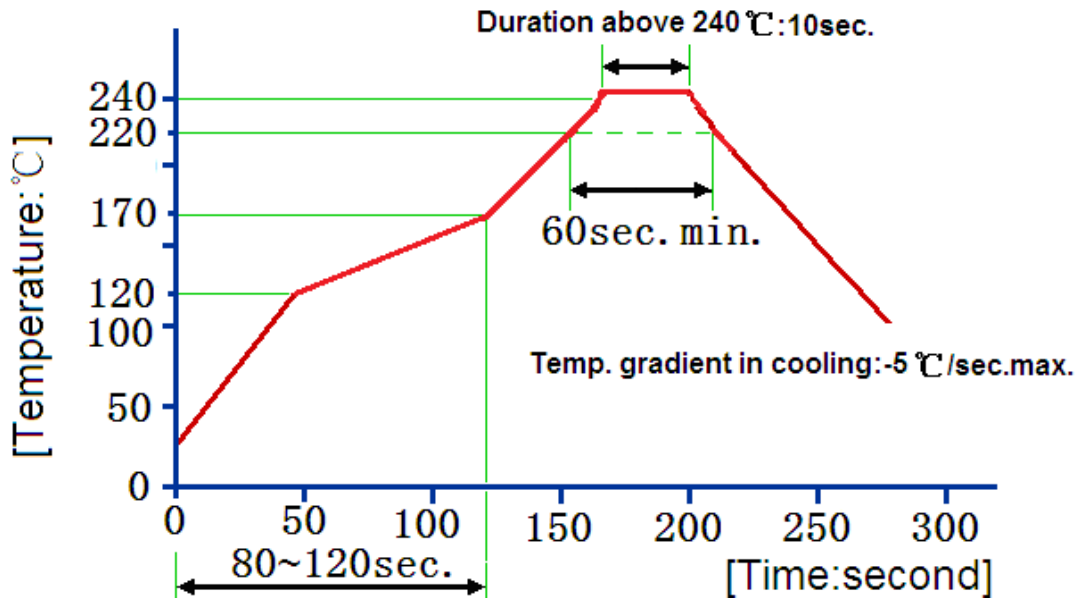
S22 Smith Chart



**Reliability (The SAW components shall remain electrical performance after tests)**

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: $85^{\circ}\text{C}\pm 2^{\circ}\text{C}$ , Duration: 250h, Recovery time: $2\text{h}\pm 0.5\text{h}$ (2) Temperature: $-55^{\circ}\text{C}\pm 3^{\circ}\text{C}$ , Duration: 250h, Recovery time: $2\text{h}\pm 0.5\text{h}$
2	Humidity Test	Conditions: $60^{\circ}\text{C}\pm 2^{\circ}\text{C}$ , 90~95% RH Duration: 250h
3	Thermal Shock	Heat cycle conditions: $T_A = -55^{\circ}\text{C}\pm 3^{\circ}\text{C}$ , $T_B = 85^{\circ}\text{C}\pm 2^{\circ}\text{C}$ , $t_1 = t_2 = 30\text{min}$ , Switch time: $\leq 3\text{min}$ , Cycle time: 100 times, Recovery time: $2\text{h}\pm 0.5\text{h}$ .
4	Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude: 1.5mm Directions: X, Y and Z Duration: 2h
5	Drop Test	Cycle time: 10 times Height: 1.0m
6	Solder Ability Test	Temperature: $245^{\circ}\text{C}\pm 5^{\circ}\text{C}$ Duration: 3.0s--5.0s Depth: DIP--2/3, SMD--1/5
7	Resistance to Soldering Heat	(1) Thickness of PCB: 1mm, Solder condition: $260^{\circ}\text{C}\pm 5^{\circ}\text{C}$ , Duration: $10\pm 1\text{s}$ (2) Temperature of Soldering Iron: $350^{\circ}\text{C}\pm 10^{\circ}\text{C}$ , Duration: 3~4s, Recovery time: $2\pm 0.5\text{h}$

**Recommended Reflow Soldering Diagram**



**Reflow cycles: 3 cycles max.**

**Notes**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.